

L Number	Hits	Search Text	DB	Time stamp
3	6	((("20040067653") or ("20030082900") or ("6548394") or ("6492211") or ("6190974") or ("5795802"))).PN.	USPAT; US-PGPUB	2004/09/03 12:12
4	7	(implant\$8 same (ILD near3 mask) same gate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 12:13
-	210	(438/142).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:23
-	1303	(438/217).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:23
-	623	(438/199).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:23
-	300	(438/233).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:23
-	504	(438/231).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:24
-	311	(438/232).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:24
-	1137	(438/301).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:24
-	2050	(438/305).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 07:41
-	460	(438/306).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:24
-	687	(438/527).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:24
-	219	(438/533).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:24
-	2162	(438/586).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:24

-	496	(438/682).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:25
-	440	(438/664).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:25
-	444	(438/649).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:25
-	1644	(438/655).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:25
-	2665	438/142,217,199,233,231,232,301,305,306,527, and gate and source and drain and silicide and (plug or contact) and @ad<=20031229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:25
-	1841	438/\$.ccls. and gate and source and drain and (light\$3 adj (dop\$5 or implant\$6)) and ((heav\$4 or deep\$3 or depth) adj (dop\$5 or implant\$6)) and silicide and (plug or contact) and @ad<=20031229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:39
-	3012	semiconductor and gate and source and drain and (light\$3 adj (dop\$5 or implant\$6)) and ((heav\$4 or deep\$3 or depth) adj (dop\$5 or implant\$6)) and silicide and (plug or contact) and @ad<=20031229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:39
-	2692	257/\$.ccls. and gate and source and drain and (light\$3 adj (dop\$5 or implant\$6)) and ((heav\$4 or deep\$3 or depth) adj (dop\$5 or implant\$6)) and silicide and (plug or contact) and @ad<=20031229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:39
-	686	438/142,217,199,233,231,232,301,305,306,527, and gate and source and drain and (light\$3 adj (dop\$5 or implant\$6)) and ((heav\$4 or deep\$3 or depth) adj (dop\$5 or implant\$6)) and silicide and (plug or contact) and @ad<=20031229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 08:25
-	8	"5739573" "5747373" "5763312" "5770508" "5780348").PN.	USPAT	2004/09/01 07:41
-	10	("4309626" "4356622" "5260595" "5316964" "5444024" "5550084" "5589423" "5773339" "5838033" "5883010").PN.	USPAT	2004/08/31 12:33
-	2	("6667233").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 12:09